



Final Product Change Notification

201709011F01

Issue Date: 20-Sep-2017

Effective Date: 18-Dec-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☒ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage

I.MX6ULL MAPBGA289
14x14 Assembly Site
Expansion from NXP-ATTJ
to ASECL

Details of this Change

NXP Semiconductor is announcing the Assembly Site Expansion from NXP Tianjin, China assembly site (NXP-ATTJ) to ASE CHUNGLI, Taiwan assembly site (ASECL) for the I.MX6ULL, 289 MAPBGA Devices.

Why do we Implement this Change

Qualification of the ASECL, Taiwan assembly site will ensure customer supply by providing manufacturing flexibility.

Identification of Affected Products

There is no change to orderable part number.

Assembly site will change in tracecode on part marking:

ATWLYYWWZ

(Assy/Test/Wafer/Year/Workweek/Assy Split)

A=CT (ATTJ assy site)

A=X (ASECL assy site)

Product Availability

Sample Information

Samples are available from 22-Sep-2017
The following sample part number is available:

PCIMX6Y2DVM05AA

Production

Planned first shipment 25-Dec-2017

Impact

There is no change to form, fit, function, or reliability.

Disposition of Old Products

NXP will reserve the right to ship from both locations based on market demand situation.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 20-Oct-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Linda Yang
Position Product Engineer
e-mail address linda.y@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[NCP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
MCIMX6Y7DVM09AA	935346023557	MCIMX6Y7DVM09AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y2DVM09AA	935346022557	MCIMX6Y2DVM09AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y2CVM08AA	935340995557	MCIMX6Y2CVM08AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y1CVM05AA	935320915557	MCIMX6Y1CVM05AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers
MCIMX6Y2DVM05AA	935313074557	MCIMX6Y2DVM05AA	i.MX6ULL	LFBGA289	RFS	BL Microcontrollers